

DESCRIPTION

The IS3H4 is an optically coupled isolator consists of two infrared emitting diodes in reverse parallel connection and optically coupled to an NPN silicon photo transistor.

This device belongs to Isocom Compact Range of Optocouplers.

FEATURES

- Half Pitch 1.27mm
- High AC Isolation voltage 3750V_{RMS}
- Wide Operating Temperature Range -55°C to 100°C
- RoHS Compliant
- UL Approval E91231, Model "AHP"

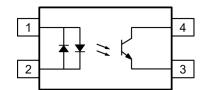
APPLICATIONS

- Telephone Line Interface
- Programmable Controllers
- Measuring Instruments
- AC Line Monitor

ORDER INFORMATION

 Available in Tape and Reel with 1000pcs per reel





- Anode / Cathode
- 2 Cathode / Anode
- 3 Emitter
- 4 Collector

ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current $\pm 50 \text{mA}$ Peak Forward Current (t=10 μ s) 1A
Power Dissipation 70mW
No Derating required up to $T_A = 100^{\circ}\text{C}$

Output

Collector to Emitter Voltage V_{CEO} 80V Emitter to Collector Voltage V_{ECO} 6V Power Dissipation 150mW Power Dissipation Derating Factor 3.7mW/°C (above $T_A = 80^{\circ}C$)

Total Package

Isolation Voltage 3750V_{RMS}

Total Power Dissipation 200mW

Operating Temperature -55 to 100 °C

Storage Temperature -55 to 125 °C

Lead Soldering Temperature (10s) 260 °C

ISOCOM COMPONENTS 2004 LTD

Unit 25B, Park View Road West, Park View Industrial Estate Hartlepool, Cleveland, TS25 1PE, United Kingdom Tel: +44 (0)1429 863 609 Fax: +44 (0)1429 863 581 e-mail: sales@isocom.co.uk http://www.isocom.com

ISOCOM COMPONENTS ASIA LTD

Hong Kong Office
Block A, 8/F, Wah Hing Industrial Mansions
36 Tai Yau Street, San Po Kong, Kowloon, Hong Kong
Tel: +852 2995 9217 Fax: +852 8161 6292
e-mail: sales@isocom.com.hk



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	V_{F}	$I_F = \pm 20 \text{mA}$		1.2	1.4	V
Input Capacitance	C_{IN}	V = 0V, $f = 1kHz$		50	250	pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector-Emitter Breakdown Voltage	BV_{CEO}	$I_C = 0.1 \text{mA}, I_F = 0 \text{ mA}$	80			V
Emitter-Collector Breakdown Voltage	$\mathrm{BV}_{\mathrm{ECO}}$	$I_E = 0.01 \text{mA}, I_F = 0 \text{mA}$	6			V
Collector-Emitter Dark Current	I_{CEO}	$V_{CE}=20V,I_F=0mA$			100	nA

COUPLED

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$	20		300	%
CTR Symmetry		$I_F = \pm 1 \text{mA}, V_{CE} = 5V$	0.5		2.0	
Collector – Emitter Saturation Voltage	V _{CE(sat)}	$I_F = \pm 20 \text{mA}, I_C = 1 \text{mA}$		0.1	0.2	V
Floating Capacitance	C_{f}	$V_{IO} = 0$, $f = 1MHz$		0.6	1.0	pF
Output Rise Time	t _r	$V_{CE} = 2V$, Ic = 2mA,			18	μs
Output Fall Time	t_{f}	$R_L = 100\Omega$			18	

ISOLATION

Parameter	Symbol	Test Condition	Min	*Тур.	Max	Unit
Input to Output Isolation Voltage	$V_{\rm ISO}$	AC 1 minute, RH = 40% to 60% Note 1	3750			V_{RMS}
Input to Output Isolation Resistance	R _{ISO}	V _{IO} = 500Vdc, RH = 40% to 60% Note 1	5x10 ¹⁰	1x10 ¹¹		Ω

Note 1: Measured with input leads shorted together and output leads shorted together, R.H 40% to 60%



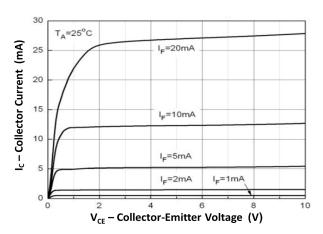


Fig 1 Collector Current vs Collector-Emitter Voltage (1)

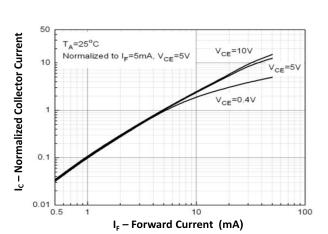


Fig 3 Normalized Collector Current vs Forward Current

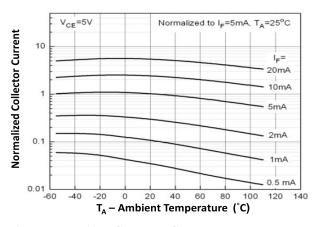


Fig 5 Normalized Collector Current vs Ambient Temperature

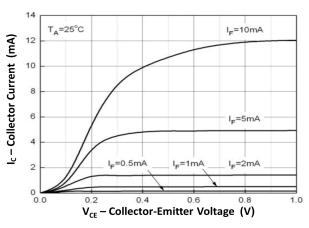


Fig 2 Collector Current vs Collector-Emitter Voltage (2)

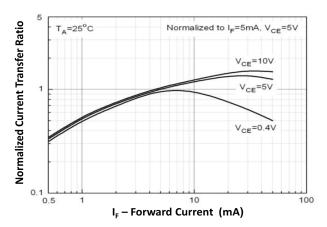


Fig 4 Normalized Current Transfer Ratio vs Forward Current

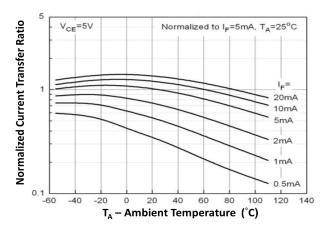


Fig 6 Normalized Current Transfer Ratio vs Ambient Temperature



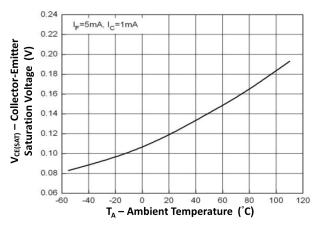


Fig 7 Collector-Emitter Saturtion Voltage vs Ambient Temperature

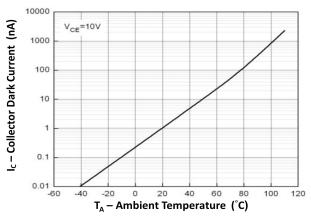
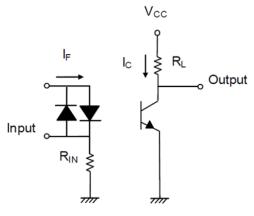


Fig 9 Collector Dark Current vs Ambient Temperature



Switching Time Test Circuit

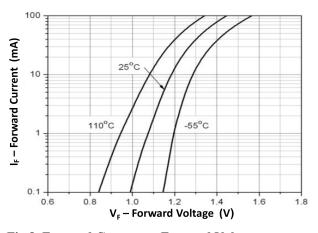


Fig 8 Forward Current vs Forward Voltage

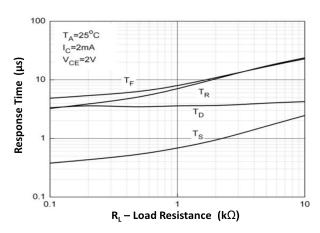
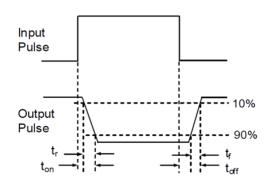


Fig 10 Response Time vs Load Resistance





ORDER INFORMATION

IS3H4			
After PN	PN	Description	Packing quantity
None	IS3H4	Surface Mount Tape & Reel	1000 pcs per reel

DEVICE MARKING



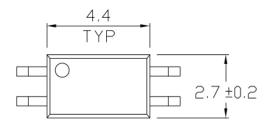
AHP1 Product Code for IS3H4

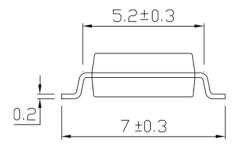
I Isocom Components 2004 Ltd.

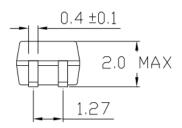
Y 1 digit Year code
WW 2 digit Week code



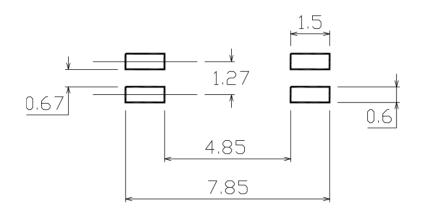
PACKAGE DIMENSIONS (mm)





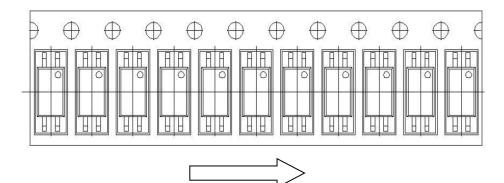


RECOMMENDED SOLDER PAD LAYOUT (mm)

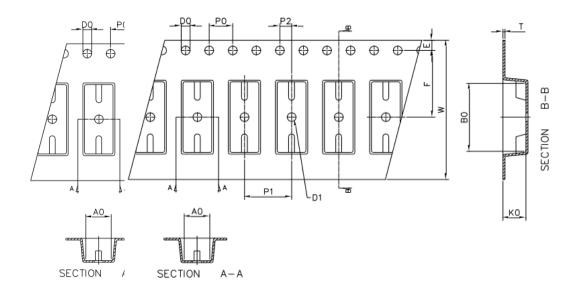




TAPE AND REEL PACKAGING



Direction of Feed from Reel

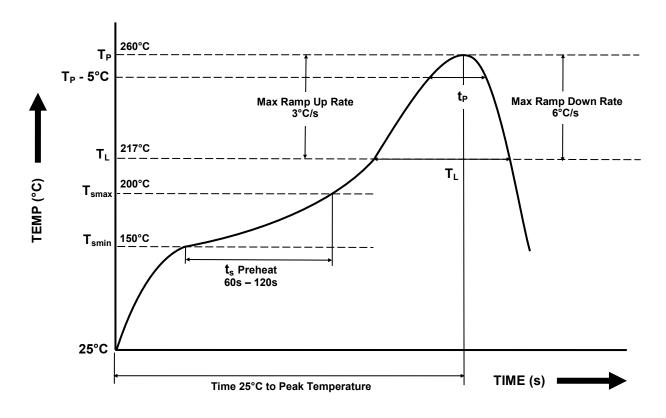


Dimension No.	Α0	В0	D0	D1	E	F
Dimension(mm)	3.00±0.10	7.45±0.10	1.50+0.1/-0	1.50±0.10	1.75±0.10	5.5±0.10
Dimension No.	P0	P1	P2	t	w	K0
Dimension (mm)	4.00±0.15	4.00±0.10	2.00±0.10	0.30±0.05	12.1±0.2	2.45±0.1



IR REFLOW SOLDERING TEMPERATURE PROFILE

One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \ \text{to } T_{SMAX} \left(t_s \right) \end{array} $	150°C 200°C 60s - 120s
$\begin{tabular}{lll} \textbf{Soldering Zone} \\ - & \text{Peak Temperature } (T_P) \\ - & \text{Liquidous Temperature } (T_L) \\ - & \text{Time within } 5^{\circ}\text{C of Actual Peak Temperature } (T_P - 5^{\circ}\text{C}) \\ - & \text{Time maintained above } T_L \ (t_L) \\ - & \text{Ramp Up Rate } (T_L \ \text{to } T_P) \\ - & \text{Ramp Down Rate } (T_P \ \text{to } T_L) \\ \end{tabular}$	260°C 217°C 30s 60s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



Disclaimer

Isocom Components is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing Isocom Components products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such Isocom Components products could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that Isocom Components products are used within specified operating ranges as set forth in the most recent Isocom Components products specifications.

The Isocom Components products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These Isocom Components products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation Instruments, traffic signal instruments, combustion control instruments, medical Instruments, all types of safety devices, etc... Unintended Usage of Isocom Components products listed in this document shall be made at the customer's own risk.

Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes are toxic. Do not break, cut or pulverize the product, or use chemicals to dissolve them. When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic garbage.

The products described in this document are subject to the foreign exchange and foreign trade laws.

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by Isocom Components for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of Isocom Components or others.

The information contained herein is subject to change without notice.